TOSHIBA CMOS Digital Integrated Circuit Silicon Monolithic

TC74VCX16646FT

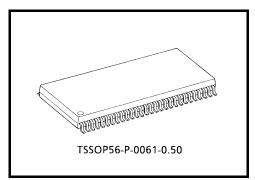
Low-Voltage 16-Bit Bus Transceiver/Register with 3.6-V Tolerant Inputs and Outputs

The TC74VCX16646FT is a high-performance CMOS 16-bit bus transceiver/register. Designed for use in 1.8-V, 2.5-V or 3.3-V systems, it achieves high-speed operation while maintaining the CMOS low power dissipation.

It is also designed with overvoltage tolerant inputs and outputs up to 3.6 V.

This device is bus transceiver with 3-state outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the internal registers.

All inputs are equipped with protection circuits against static discharge.



Weight: 0.25 g (typ.)

Features (Note)

- Low-voltage operation: V_{CC} = 1.8 to 3.6 V
- High-speed operation: $t_{pd} = 2.9 \text{ ns} (\text{max}) (V_{CC} = 3.0 \text{ to } 3.6 \text{ V})$

: t_{pd} = 3.5 ns (max) (V_{CC} = 2.3 to 2.7 V)

$$t_{pd}$$
 = 7.0 ns (max) (V_{CC} = 1.8 V)

- Output current: $I_{OH}/I_{OL} = \pm 24 \text{ mA} \text{ (min)} (V_{CC} = 3.0 \text{ V})$
 - $: I_{OH}/I_{OL} = \pm 18 \text{ mA (min)} (V_{CC} = 2.3 \text{ V})$
 - $: I_{OH}/I_{OL} = \pm 6 \text{ mA (min)} (V_{CC} = 1.8 \text{ V})$
- Latch-up performance: ±300 mA
- ESD performance: Machine model > ±200 V

: Human body model > ± 2000 V

- Package: TSSOP (thin shrink small outline package)
- Bidirectional interface between 2.5 V and 3.3 V signals.
- 3.6-V tolerant function and power-down protection provided on all inputs and outputs

Note: Do not apply a signal to any bus pins when it is in the output mode. Damage may result.

All floating (high impedance) bus pins must have their input level fixed by means of pull-up or pull-down resistors.

Pin Assignment (top view)

	1			
1DIR	1	0	56	1 0E
1CAB	2		55	1CBA
1SAB	3		54	1SBA
GND	4		53	GND
1A1	5		52	1B1
1A2	6		51	1B2
V _{CC}	7		50	V _{CC}
1A3	8		49	1B3
1A4	9		48	1B4
1A5	10		47	1B5
GND	11		46	GND
1A6	12		45	1B6
1A7	13		44	1B7
1A8	14		43	1B8
2A1	15		42	2B1
2A2	16		41	2B2
2A3	17		40	2B3
GND	18		39	GND
2A4	19		38	2B4
2A5	20		37	2B5
2A6	21		36	2B6
V _{CC}	22		35	V _{CC}
2A7	23		34	2B7
2A8	24		33	2B8
GND	25		32	GND
2SAB	26		31	2SBA
2CAB	27		30	2CBA
2DIR	28		29	20E

IEC Logic Symbol

10E - 1DIR -	1		G3 3EN1 (B/ 3EN2 (Al					
1CBA -	55		≻C4					
1SBA -	54		G5					
1CAB-	2		C6					
1SAB -	3		G7					
20E -	29		G10					
2DIR -	28		10EN8 (E	SA)				
2011			10EN9 (A					
2CBA-	30		>C11	(2)				
2SBA-	31		G12					
	27							
2CAB -	26		>C13					
2SAB -			G14					
					Г		52	
1A1 -	5	→	≥ 1		4D	• • •	- 52	- 1B1
			∇ 1	51				
			6D 7	≥ 1				
			1 7	2	∇			
	6						51	
1A2 -	0	\leftrightarrow			ŀ		> 51	- 1B2
	•						10	
1A3 -	8	\leftrightarrow			ŀ		→ ⁴⁹	- 1B3
					_			
1A4 -	9	\leftrightarrow			-		<u>→ 48</u>	- 1B4
					_			
1A5 -	10	\leftrightarrow					47	- 1B5
1A6 -	12	\rightarrow					45	- 1B6
1710							-	100
1A7 -	13						44	- 1B7
IA/ -		\sim						- 10/
1A8 -	14						43	- 1B8
1A8 -		\leftrightarrow			Ī			
2A1 -	15		≥ 1	12 1 [.]	1D -	• < •	42	-2B1
2A1 -		\rightarrow	∀ 8	12 1	-			
			13D 14	≥ 1				
			14 1		\bigtriangledown			
		-						
2A2 -	16	\leftrightarrow			-		× 41	- 2B2
					_			
2A3 -	17	\leftrightarrow					40	- 2B3
244 -	19	\rightarrow					> 38	- 2R4
2/14								204
045	20	\leftrightarrow					37	005
ZAD -		\sim						- 200
	21	\leftrightarrow					36	
2A6 -	21	\leftrightarrow			t		> •••	- 2B6
	22						21	
2A7 -	23	\leftrightarrow			ŀ		34	- 2B7
							~~	
2A8 -	24	\leftrightarrow			┝		> 33	- 2B8

Truth Table

		Contro	l Inputs			В	us	Function	
ŌĒ	DIR	CAB	CBA	SAB	SBA	А	В	Function	
		Х*	X*	х	х	Input	Input	The output functions of A and B Busses are	
н	x	~	~	~		Z	Z	disabled.	
п	^	Ļ		х	х	х	х	Both A and B Busses are used as inputs to the internal flip-flops. Data on the Bus will be stored on the rising edge of the Clock.	
						Input	Output		
		X*	X*	L	х	L	L	The data on the A bus are displayed on the B bus.	
						Н	Н		
			X*	L	~	L	L	The data on the A bus are displayed on the	
L	н		^ *	L	Х	н	н	B Bus, and are stored into the A storage flip-flops on the rising edge of CAB.	
		X*	X*	Н	х	х	Qn	The data in the A storage flop-flops are displayed on the B Bus.	
							L	L	The data on the A Bus are stored into the A
			X*	Н	Х	н	Н	storage flip-flops on the rising edge of CAB, and the stored data propagate directly onto the B Bus.	
						Output	Input		
		X*	X*	х	L	L	L	The data on the B Bus are displayed on the A bus.	
						Н	Н		
		X*		х	L	L	L	The data on the B Bus are displayed on the A Bus, and are stored into the B storage	
L	L	^ .				н	н	flip-flops on the rising edge of CBA.	
		X*	X*	х	Н	Qn	х	The data in the B storage flip-flops are displayed on the A Bus.	
			_			L	L	The data on the B Bus are stored into the B	
		Х*		Х	Н	Н	Н	storage flip-flops on the rising edge of CBA, and the stored data propagate directly onto the A Bus.	

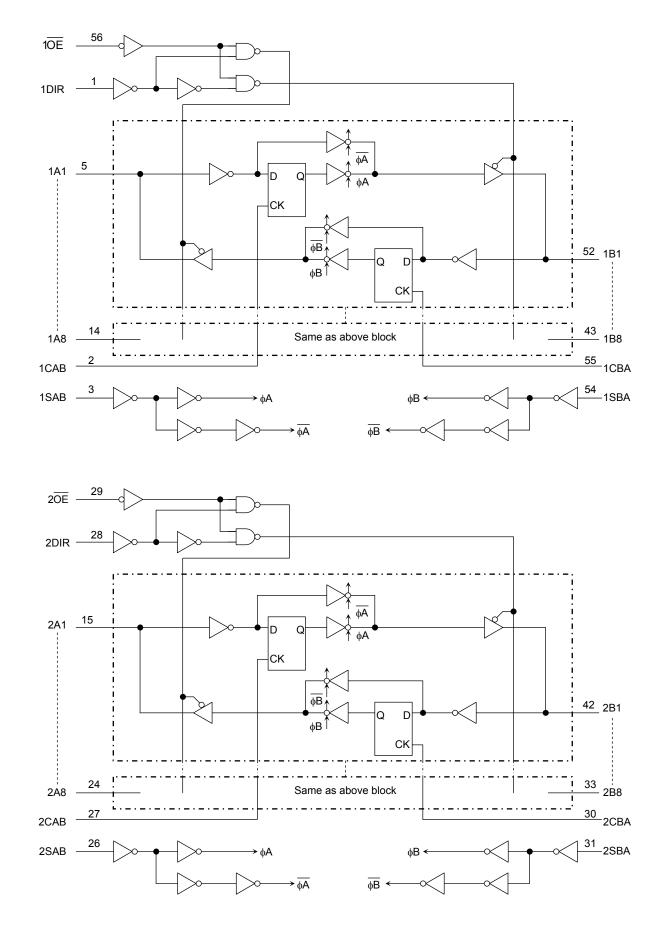
X: Don't care

Z: High impedance

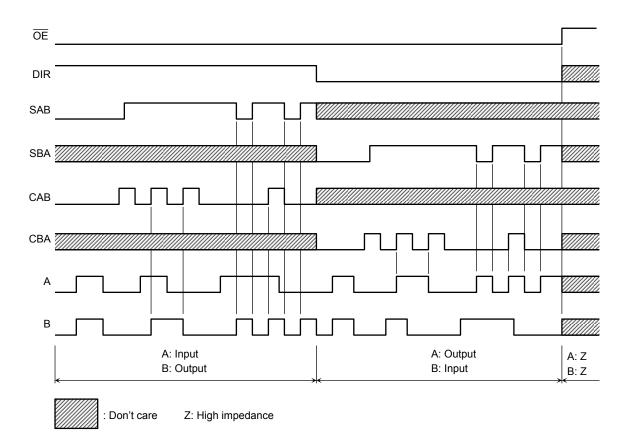
Qn: The data stored into the internal flip-flops by most recent low to high transition of the clock inputs.

*: The clocks are not internally with either \overline{OE} or DIR. Thefore, data on the A and/or B busses may be clocked into the storage flip-flops at any time.

System Diagram



Timing Chart



Absolute Maximum Ratings (Note 1)

Characteristics	Symbol	Rating	Unit
Power supply voltage	V _{CC}	-0.5 to 4.6	V
DC input voltage (DIR, OE, CAB, CBA, SAB, SBA)	V _{IN}	–0.5 to 4.6	V
		-0.5 to 4.6 (Note 2)	
DC bus I/O voltage	V _{I/O}	–0.5 to V _{CC} + 0.5	V
		(Note 3)	
Input diode current	IIK	-50	mA
Output diode current	IOK	±50 (Note 4)	mA
DC output current	IOUT	±50	mA
Power dissipation	PD	400	mW
DC V_{CC} /ground current per supply pin	I _{CC} /I _{GND}	±100	mA
Storage temperature	T _{stg}	–65 to 150	°C

Note 1: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Note 2: OFF state

Note 3: High or low state. IOUT absolute maximum rating must be observed.

Note 4: $V_{OUT} < GND, V_{OUT} > V_{CC}$

Recommended Operating Range (Note 1)

Characteristics	Symbol	Rating	Unit	
Power supply voltage	V _{CC}	1.8 to 3.6	V	
Tower supply voltage	v CC	1.2 to 3.6 (Note 2)	v	
Input voltage (DIR, OE, CAB, CBA, SAB, SBA)	V _{IN}	-0.3 to 3.6	V	
Bus I/O voltage	V _{I/O}	0 to 3.6 (Note 3)	V	
Bus i/O voltage	VI/O	0 to V _{CC} (Note 4)		
		±24 (Note 5)		
Output current	I _{OH} /I _{OL}	±18 (Note 6)	mA	
		±6 (Note 7)		
Operating temperature	T _{opr}	-40 to 85	°C	
Input rise and fall time	dt/dv	0 to 10 (Note 8)	ns/V	

Note 1: The recommended operating conditions are required to ensure the normal operation of the device. Unused inputs must be tied to either VCC or GND.

- Note 2: Data retention only
- Note 3: OFF state
- Note 4: High or low state
- Note 5: $V_{CC} = 3.0$ to 3.6 V
- Note 6: $V_{CC} = 2.3$ to 2.7 V
- Note 7: $V_{CC} = 1.8 V$
- Note 8: $V_{IN} = 0.8$ to 2.0 V, $V_{CC} = 3.0$ V

Electrical Characteristics

DC Characteristics (Ta = –40 to 85°C, 2.7 V < V_{CC} \leq 3.6 V)

Characte	rictice	Symbol Test Condition				Min	Мах	Unit
Gharacteristics		Symbol rest Condition		V _{CC} (V)	IVIIII	IVIAX	Unit	
Input voltage	H-level	VIH		_	2.7 to 3.6	2.0		V
input voltage	L-level	VIL		_	2.7 to 3.6		0.8	v
H-level Output voltage			I _{OH} = -100 μA	2.7 to 3.6	V _{CC} - 0.2	_		
	Vон	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -12 mA	2.7	2.2	_		
	OIT		I _{OH} = -18 mA	3.0	2.4	_		
			I _{OH} = -24 mA	3.0	2.2		V	
	Mai	VIN = VIH or VII	I _{OL} = 100 μA	2.7 to 3.6	_	0.2		
			I _{OL} = 12 mA	2.7	_	0.4		
	L-level	V _{OL}	VIN = VIH OL VIL	I _{OL} = 18 mA	3.0	_	0.4	
				I _{OL} = 24 mA	3.0	_	0.55	
Input leakage curre	ent	I _{IN}	V _{IN} = 0 to 3.6 V		2.7 to 3.6		±5.0	μA
3-state output OFF state current		I _{OZ}	$V_{IN} = V_{IH} \text{ or } V_{IL}$		2.7 to 3.6		±10.0	μA
Power-off leakage	current	IOFF	V _{OUT} = 0 to 3.6 V V _{IN} , V _{OUT} = 0 to 3.6 V		0		10.0	μA
			$V_{IN} = V_{CC}$ or GND		2.7 to 3.6	_	20.0	
Quiescent supply of	current	ICC	$V_{CC} \leq (V_{IN}, V_{OUT}) \leq 3.6 V$		2.7 to 3.6	_	±20.0	μA
Increase in I _{CC} pe	r input	Δlcc	$V_{IH} = V_{CC} - 0.6 V$		2.7 to 3.6		750	

DC Characteristics (Ta = -40 to 85°C, 2.3 V \leq V_{CC} \leq 2.7 V)

Characteristics S		Symbol	Test Condition		V _{CC} (V)	Min	Max	Unit
Input voltago	H-level	VIH		_	2.3 to 2.7	1.6	_	V
Input voltage	L-level	VIL	-		2.3 to 2.7	_	0.7	v
				I _{OH} = -100 μA	2.3 to 2.7	V _{CC} - 0.2	_	
H-level Output voltage	H-level	Vон	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I _{OH} = -6 mA	2.3	2.0	_	
				I _{OH} = -12 mA	2.3	1.8	_	v
				I _{OH} = -18 mA	2.3	1.7	_	
		V _{OL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 100 μA	2.3 to 2.7	_	0.2	
	L-level			I _{OL} = 12 mA	2.3	_	0.4	
				I _{OL} = 18 mA	2.3	_	0.6	
Input leakage curre	ent	I _{IN}	V _{IN} = 0 to 3.6 V		2.3 to 2.7	_	±5.0	μA
	- atata aurrant	1	$V_{IN} = V_{IH} \text{ or } V_{IL}$	$V_{IN} = V_{IH} \text{ or } V_{IL}$			±10.0	
3-state output OFF state current		loz	V _{OUT} = 0 to 3.6 V		2.3 to 2.7	—	±10.0	μA
Power-off leakage	current	IOFF	V_{IN} , $V_{OUT} = 0$ to 3.6 V		0		10.0	μA
Quiescent supply of	ourront		$V_{IN} = V_{CC}$ or GND		2.3 to 2.7	_	20.0	
Quiescent supply (Icc	$V_{CC} \leq (V_{IN}, V_{OUT}) \leq 3.$	6 V	2.3 to 2.7		±20.0	μA

DC Characteristics (Ta = -40 to 85°C, 1.8 V \leq V_{CC} < 2.3 V)

Characteris	stics	Symbol	Test Co	Test Condition		Min	Max	Unit	
Input voltage	H-level	VIH	-	_	1.8 to 2.3	0.7 × V _{CC}	_	V	
mput voltage	L-level	VIL	-	_	1.8 to 2.3		$0.2 \times V_{CC}$	v	
	H-level	V _{OH}	VIN = VIH or VII	I _{OH} = -100 μA	1.8	V _{CC} - 0.2	_		
Output voltage	Output voltage			I _{OH} = -6 mA	1.8	1.4	_	V	
	L-level	Voi		I _{OL} = 100 μA	1.8	_	0.2		
	L-IEVEI	VOL	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 6 mA	1.8		0.3		
Input leakage currer	nt	I _{IN}	V _{IN} = 0 to 3.6 V		1.8		±5.0	μA	
3-state output OFF	state current	I _{OZ}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $V_{OUT} = 0 \text{ to } 3.6 \text{ V}$		1.8	—	±10.0	μA	
Power-off leakage c	urrent	IOFF	V_{IN} , $V_{OUT} = 0$ to 3.6 V		0		10.0	μA	
	urrent	Icc	$V_{IN} = V_{CC}$ or GND		1.8		20.0	A	
Quescent supply cu	Quiescent supply current		$V_{CC} \leq (V_{IN}, V_{OUT}) \leq 3.6 \text{ V}$		1.8		±20.0	μA	

AC Characteristics (Ta = -40 to 85°C, input: $t_r = t_f = 2.0$ ns, $C_L = 30$ pF, $R_L = 500 \Omega$) (Note 1)

Characteristics	Symbol	Test Condition		Min	Max	Unit
Characteristics	Symbol	Test Condition	$V_{CC}(V)$	IVIIII	Wax	Unit
			1.8	100	_	MHz
Maximum clock frequency	f _{max}	Figure 1, Figure 3	2.5 ± 0.2	200	_	
			$\textbf{3.3}\pm\textbf{0.3}$	250		
Descention delay firm			1.8	1.5	7.0	
Propagation delay time	t _{pLH}	Figure 1, Figure 2	2.5 ± 0.2	0.8	3.5	ns
(An, Bn-Bn, An)	t _{pHL}		$\textbf{3.3}\pm\textbf{0.3}$	0.6	2.9	
Dranamation delay time			1.8	1.5	8.8	
Propagation delay time		Figure 1, Figure 3	2.5 ± 0.2	0.8	4.4	ns
(CAB, CBA-Bn, An)	t _{pHL}		$\textbf{3.3}\pm\textbf{0.3}$	0.6	3.2	
Dranamatian dalay time			1.8	1.5	8.8	
Propagation delay time (SAB, SBA-Bn, An)	t _{pLH}	Figure 1, Figure 2	2.5 ± 0.2	0.8	4.4	ns
	t _{pHL}		$\textbf{3.3}\pm\textbf{0.3}$	0.6	3.5	
		Figure 1, Figure 4, Figure 5	1.8	1.5	9.8	
Output enable time (OE , DIR-An, Bn)	t _{pZL}		2.5 ± 0.2	0.8	4.9	ns
(UE , DIR-AII, BII)	^t pZH		$\textbf{3.3}\pm\textbf{0.3}$	0.6	3.8	
Output dischla time		Figure 1, Figure 4, Figure 5	1.8	1.5	7.6	ns
Output disable time (OE , DIR-An, Bn)	t _{pLZ}		2.5 ± 0.2	0.8	4.2	
(UE, DIR-AII, BII)	^t pHZ		$\textbf{3.3}\pm\textbf{0.3}$	0.6	3.7	
			1.8	4.0	_	
Minimum pulse width	^t w (H)	Figure 1, Figure 3	2.5 ± 0.2	1.5	_	ns
	t _{w (L)}		$\textbf{3.3}\pm\textbf{0.3}$	1.5	_	
			1.8	2.5	_	
Minimum setup time	ts	Figure 1, Figure 3	2.5 ± 0.2	1.5	_	ns
			$\textbf{3.3}\pm\textbf{0.3}$	1.5	_	
Minimum hold time			1.8	1.0		
	t _h	Figure 1, Figure 3	2.5 ± 0.2	1.0		ns
			$\textbf{3.3}\pm\textbf{0.3}$	1.0		
	+		1.8	_	0.5	
Output to output skew	t _{osLH}	(Note 2)	2.5 ± 0.2	_	0.5	ns
	t _{osHL}		$\textbf{3.3}\pm\textbf{0.3}$	_	0.5	

Note 1: For $C_L = 50 \text{ pF}$, add approximately 300 ps to the AC maximum specification.

Note 2: Parameter guaranteed by design. $(t_{osLH} = |t_{pLHm} - t_{pLHn}|, \ t_{osHL} = |t_{pHLm} - t_{pHLn}|)$

Dynamic Switching Characteristics

(Ta = 25°C, input: $t_r = t_f = 2.0$ ns, $C_L = 30$ pF, $R_L = 500 \Omega$)

Characteristics	Symbol	Test Condition			Тур.	Unit	
				$V_{CC}(V)$			
		$V_{IH} = 1.8 \text{ V}, V_{IL} = 0 \text{ V}$	(Note)	1.8	0.25		
Quiet output maximum dynamic V _{OL}	V _{OLP}	$V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$	(Note)	2.5	0.6	V	
		$V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$	(Note)	3.3	0.8		
		$V_{IH} = 1.8 \text{ V}, V_{IL} = 0 \text{ V}$	(Note)	1.8	-0.25		
Quiet output minimum dynamic V _{OI}	V _{OLV}	$V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$	(Note)	2.5	-0.6	V	
,		$V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$	(Note)	3.3	-0.8		
		$V_{IH} = 1.8 \text{ V}, V_{IL} = 0 \text{ V}$	(Note)	1.8	1.5		
Quiet output minimum dynamic V _{OH}	VOHV	$V_{IH} = 2.5 V, V_{IL} = 0 V$	(Note)	2.5	1.9	V	
		$V_{IH} = 3.3 V, V_{IL} = 0 V$	(Note)	3.3	2.2		

Note: Parameter guaranteed by design.

Capacitive Characteristics (Ta = 25°C)

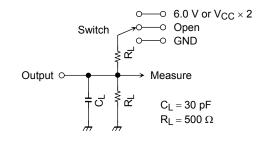
Characteristics	Symbol	Test Condition	[V _{CC} (V)	Тур.	Unit
Input capacitance	C _{IN}	(DIR, OE, CAB, CBA, SAB, SBA)		1.8, 2.5, 3.3	6	pF
Bus I/O capacitance	C _{I/O}	_		1.8, 2.5, 3.3	7	pF
Power dissipation capacitance	C _{PD}	$f_{IN} = 10 \text{ MHz}$ (N	lote)	1.8, 2.5, 3.3	20	pF

Note: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation:

 $I_{CC (opr)} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/16 \text{ (per bit)}$

AC Test Circuit



Parameter	Switch				
t _{pLH} , t _{pHL}	Open				
t _{pLZ} , t _{pZL}					
t _{pHZ} , t _{pZH}	GND				



AC Waveform

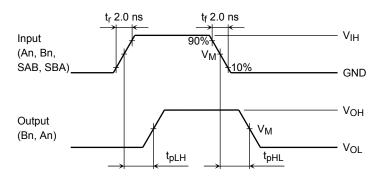


Figure 2 t_{pLH}, t_{pHL}

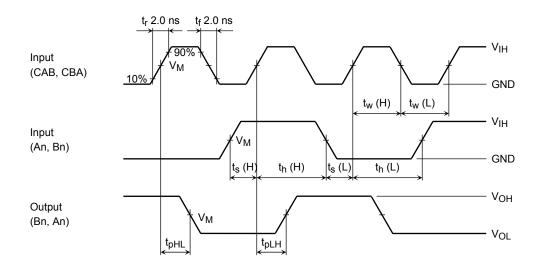
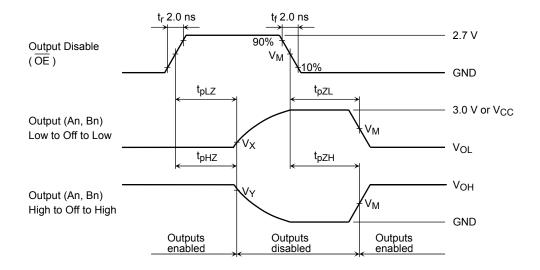
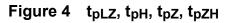
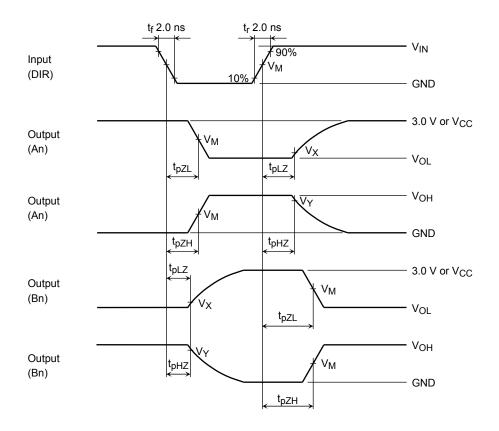
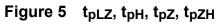


Figure 3 $t_{pLH}, t_{pHL}, t_w, t_s, t_h$





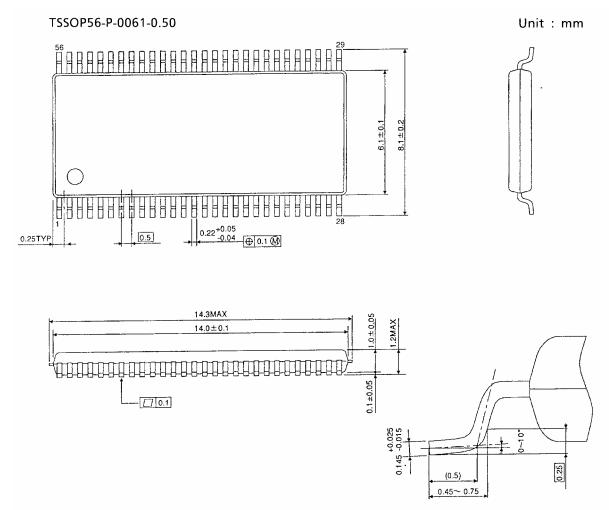




Symbol	V _{CC}		
	$3.3\pm0.3~\text{V}$	$2.5\pm0.2~V$	1.8 V
VIH	2.7 V	V _{CC}	V _{CC}
VM	1.5 V	V _{CC} /2	V _{CC} /2
VX	V _{OL} + 0.3 V	V _{OL} + 0.15 V	V _{OL} + 0.15 V
VY	V _{OH} – 0.3 V	V _{OH} – 0.15 V	V _{OH} – 0.15 V

<u>TOSHIBA</u>

Package Dimensions



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Weight: 0.25 g (typ.)
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Note: Lead (Pb)-Free Packages TSSOP56-P-0061-0.50

RESTRICTIONS ON PRODUCT USE

20070701-EN

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